

Title (en)
MEASUREMENT OF COMPONENTS THAT HAVE BEEN MICRO-GALVANICALLY PRODUCED, USING A SAMPLE COMPONENT BY MEANS OF PHOTORESIST WEBS

Title (de)
VERMESSEN VON MIKROGALVANISCH HERGESTELLTEN BAUTEILEN DURCH SCHNITTBAUTEILE ÜBER LACKSTEGE

Title (fr)
MESURE DE PIECES FABRIQUEES PAR MICROGALVANISATION, AU MOYEN DE PIECES D'INTERSECTION SUR ARETES DE VERNIS

Publication
EP 1381824 B1 20050406 (DE)

Application
EP 02729860 A 20020409

Priority
• DE 0201289 W 20020409
• DE 10118274 A 20010412

Abstract (en)
[origin: DE10118274A1] Process for measuring micro-galvanically produced components having a three-dimensional deep-lithographically produced structure comprises forming a single or multiple layer component (23') by galvanic metal deposition; inserting a photoresist region (45); removing the photoresist region from the component; and measuring the opening structure in the region of previous lacquered edge (46) of the photoresist region using a measuring device. Preferred Features: The measuring device is a scanning electron microscope, a profile projector, a CCD or IR camera, or a microscope.

IPC 1-7
G01B 11/00; **C25D 1/00**; **G03F 7/00**; **F02M 61/00**; **B05B 1/00**

IPC 8 full level
G01B 11/00 (2006.01); **B05B 1/00** (2006.01); **C25D 1/00** (2006.01); **C25D 21/12** (2006.01); **F02M 51/06** (2006.01); **F02M 61/00** (2006.01); **F02M 61/16** (2006.01); **F02M 61/18** (2006.01); **F02M 65/00** (2006.01); **G01B 11/06** (2006.01); **G01B 11/26** (2006.01); **G03F 7/00** (2006.01)

CPC (source: EP US)
C25D 21/12 (2013.01 - EP US); **F02M 51/0671** (2013.01 - EP US); **F02M 61/166** (2013.01 - EP US); **F02M 61/168** (2013.01 - EP US); **F02M 61/1853** (2013.01 - EP US); **F02M 65/00** (2013.01 - EP US); **F02M 2200/9038** (2013.01 - EP US); **F02M 2200/9046** (2013.01 - EP US)

Designated contracting state (EPC)
DE FR GB IT

DOCDB simple family (publication)
DE 10118274 A1 20021017; DE 50202720 D1 20050512; EP 1381824 A1 20040121; EP 1381824 B1 20050406; JP 2004518827 A 20040624; JP 4154240 B2 20080924; US 2004026373 A1 20040212; US 6854347 B2 20050215; WO 02084212 A1 20021024

DOCDB simple family (application)
DE 10118274 A 20010412; DE 0201289 W 20020409; DE 50202720 T 20020409; EP 02729860 A 20020409; JP 2002581920 A 20020409; US 29798102 A 20021211